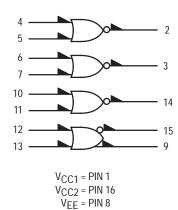
# **Quad 2-Input NOR Gate**

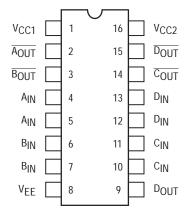
The MC10102 is a quad 2—input NOR gate. The MC10102 provides one gate with OR/NOR outputs.

- PD = 25 mW typ/gate (No Load)
- $t_{pd} = 2.0 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%-80%)

#### LOGIC DIAGRAM



#### DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



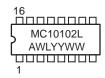
### ON Semiconductor

http://onsemi.com

#### MARKING DIAGRAMS

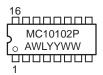


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping		
MC10102L	CDIP-16	25 Units / Rail		
MC10102P	PDIP-16	25 Units / Rail		
MC10102FN	PLCC-20	46 Units / Rail		

### **ELECTRICAL CHARACTERISTICS**

		Te				Test Limits					
Characteristic			Pin Under Test	-30°C		+25°C		+85°C		1	
		Symbol		Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply	Drain Current	ΙE	8		29		20	26		29	mAdc
Input Current		l <sub>inH</sub>	12		425			265		265	μAdc
		l <sub>inL</sub>	12	0.5		0.5			0.3		μAdc
Output Voltage	e Logic 1	VOH	9 9 15 15	-1.060 -1.060 -1.060 -1.060	-0.890 -0.890 -0.890 -0.890	-0.960 -0.960 -0.960 -0.960		-0.810 -0.810 -0.810 -0.810	-0.890 -0.890 -0.890 -0.890	-0.700 -0.700 -0.700 -0.700	Vdc
Output Voltage	e Logic 0	VOL	9 9 15 15	-1.890 -1.890 -1.890 -1.890	-1.675 -1.675 -1.675 -1.675	-1.850 -1.850 -1.850 -1.850		-1.650 -1.650 -1.650 -1.650	-1.825 -1.825 -1.825 -1.825	-1.615 -1.615 -1.615 -1.615	Vdc
Threshold Vol	tage Logic 1	VOHA	9 9 15 15	-1.080 -1.080 -1.080 -1.080		-0.980 -0.980 -0.980 -0.980			-0.910 -0.910 -0.910 -0.910		Vdc
Threshold Vol	tage Logic 0	VOLA	9 9 15 15		-1.655 -1.655 -1.655 -1.655			-1.630 -1.630 -1.630 -1.630		-1.595 -1.595 -1.595 -1.595	Vdc
Switching Tim	es (50Ω Load)										ns
Propagation D	Delay	t <sub>12+15</sub> - t <sub>12-15+</sub> t <sub>12+9+</sub> t <sub>12-9</sub> -	15 15 9 9	1.0 1.0 1.0 1.0	3.1 3.1 3.1 3.1	1.0 1.0 1.0 1.0	2.0 2.0 2.0 2.0	2.9 2.9 2.9 2.9	1.0 1.0 1.0 1.0	3.3 3.3 3.3 3.3	
Rise Time	(20 to 80%)	<sup>t</sup> 15+ t <sub>9+</sub>	15 9	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	
Fall Time	(20 to 80%)	t <sub>15</sub> _ t <sub>9</sub> _	15 9	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	

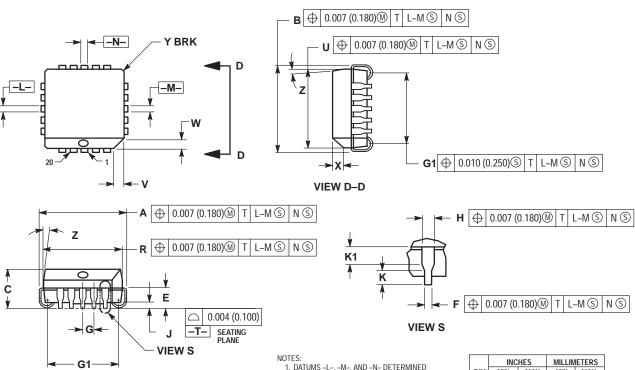
#### **ELECTRICAL CHARACTERISTICS** (continued)

					TEST VO	LTAGE VALU	JES (Volts)		
		@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin Under	TEST VOLTAGE APPLIED TO PINS LISTED BELOW					
Characteristic		Symbol	Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE	(VCC) Gnd
Power Supply Drain (	Current	ΙΕ	8					8	1, 16
Input Current		linH	12	12				8	1, 16
		l <sub>inL</sub>	12		12			8	1, 16
Output Voltage	Logic 1	VOH	9 9 15 15	12 13				8 8 8	1, 16 1, 16 1, 16 1, 16
Output Voltage	Logic 0	V <sub>OL</sub>	9 9 15 15	12 13				8 8 8 8	1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 1	VOHA	9 9 15 15			12 13	12 13	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	VOLA	9 9 15 15			12 13	12 13	8 8 8	1, 16 1, 16 1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		<sup>t</sup> 12+15– <sup>t</sup> 12–15+ <sup>t</sup> 12+9+ <sup>t</sup> 12–9–	15 15 9 9			12 12 12 12	15 15 9 9	8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t <sub>15+</sub> t <sub>9+</sub>	15 9			12 12	15 9	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t <sub>15</sub> _ tg_	15 9			12 12	15 9	8 8	1, 16 1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑥

- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

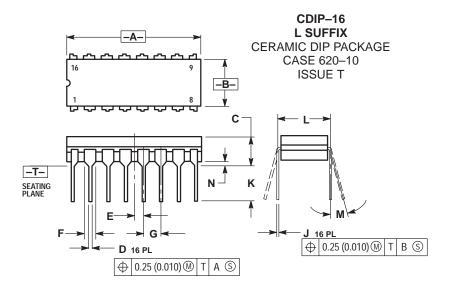
  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD.
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE. 4. DIMENSIONING AND TOLERANCING PER ANSI

- 4. DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH. 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300).
  DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMAICH BE I WEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

  7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
V	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

#### **PACKAGE DIMENSIONS**

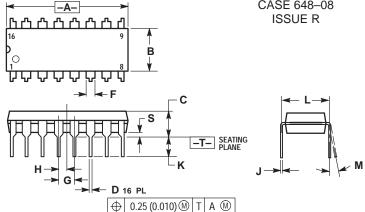


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS			
DIM	MIN MAX		MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
С		0.200		5.08		
D	0.015	0.020	0.39	0.50		
Е	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300	BSC	7.62	BSC		
M	0°	15°	0°	15°		
N	0.020	0.040	0.51	1.01		

## PDIP-16 **P SUFFIX**

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**

# **Notes**

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